

## Special Issue on InterPACK 2019 – Part 1

The International Technical Conference on Packaging and Integration of Electronic and Photonic Microsystems (InterPACK) is the premier international conference for exchange of state-of-the-art knowledge in research, development, manufacturing, and applications of electronics and photonics packaging and heterogeneous integration. Founded in 1992, InterPACK is the flagship conference for the American Society of Mechanical Engineers (ASME) Electronic and Photonic Packaging Division (EPPD). The 2019 ASME InterPACK Conference was held in Anaheim, CA, Oct. 7–9, 2019. The conference featured 235 technical papers and presentations, close to 100 posters, as well as tutorials, panels, workshops, and keynotes aligned with the areas of heterogeneous integration, servers of the future, edge and cloud computing, internet of things, flexible and wearable electronics, photonics and optics, power electronics, energy conversion and storage, and autonomous, hybrid, and electric vehicles.

The two-part 2019 InterPACK Special Issues of the ASME *Journal of Electronic Packaging* (JEP) was developed from manuscripts submitted by authors of technical papers and presentations in response to the open solicitation following the conference. All submitted manuscripts were subject to an independent peer-review process in accordance with the editorial standards of the ASME JEP. The accepted articles cover all the topics that are mentioned in the prior paragraph. It is expected that this collection of papers will serve as a high quality, informative resource for EPPD members, as well as the broader research and engineering community. We would like to sincerely thank all the authors who contributed to the Special Issues, and the reviewers who provided

critical feedback to enhance the quality of the final manuscripts. Thanks also to former JEP Editor Professor Y. C. Lee and Assistant Jeffery Lo for their support in this endeavor.

We hope that you find the content of the Special Issues useful and wish you the very best.

**Sreekant Narumanchi**  
National Renewable Energy Laboratory,  
Golden, CO 80401

**Sukwon Choi**  
Pennsylvania State University,  
University Park, PA 16802

**Saket Karajgikar**  
Facebook, Inc.,  
Fremont, CA 94555

**Haiding Sun**  
University of Science and Technology of China,  
Hefei 230026, China

**Guangsheng Zhang**  
The University of Alabama in Huntsville,  
Huntsville, AL 35899

---

This work was authored, in part, by the National Renewable Energy Laboratory, operated by the Alliance for Sustainable Energy, LLC, for the U.S. Department of Energy (DOE) under Contract No. DE-AC36-08GO28308. The views expressed in the article do not necessarily represent the views of the DOE or the U.S. Government. The U.S. Government retains, and by accepting the article for publication, the publisher acknowledges that the U.S. Government retains, a nonexclusive, paid-up, irrevocable, worldwide license to publish or reproduce the published form of this work, or allow others to do so, for U.S. Government purposes.